

## SERVICES

## MICROELECTRONICS PACKAGING

KEEPING YOU AHEAD



### ABOUT US

From our demo lab in Eindhoven (NL) our experienced Application Engineers are able to offer Microelectronics Packaging Services.

Technical advise, flexibility, quality, fast delivery and a good and long term relation with our clients are the keywords for a successful cooperation.

- ▲ Product and process demonstrations
- ▲ Single prototype production
- ▲ Low volume production
- ▲ Process development and trainings

With our network of equipment manufacturers and local partners we are able to offer a solution for many Micro Electronics Packaging challenges.

For more information please feel free to contact us.

### DIE BONDING / EPOXY BONDING

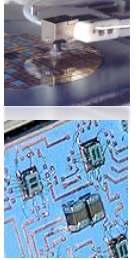
For specialistic prototypes to low/mid volume production.

Automatic accurate epoxy bonding : GaAs, Silicon, Glass Dies

- ▲ Pickup from wafer, wafer of Gel Pak
- ▲ Component size from 0.2 mm to > 50mm
- ▲ Programmable Pattern Dispensing
- ▲ Handles CCD and other sensors, LCD's MEMS.
- ▲ Unique Die Stacking with Bond line Thickness.

**Applications :**

- ▲ Chip on Board (COB)
- ▲ Chip on Flex (COF)
- ▲ Chip on Glass (COG)
- ▲ Chip in Package (Ceramic, Metal and Plastic)
- ▲ Many more.....



### FINE WIRE BONDING

For specialistic prototypes to low volume production

**Wedge-Wedge Bonding**

- ▲ Aluminum en gold wires

**Ball-Wedge Bonding**

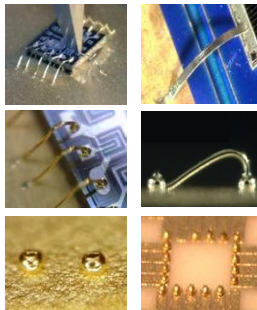
- ▲ Gold wires

**Gold Bump Bonding**

- ▲ Flip Chip technology

**Ribbon bonding**

- ▲ Microwave en RF technology
- ▲ Gold ribbon



### HEAVY WIRE BONDING

For specialistic prototypes to low volume production

Accelonix has experience in the wire bonding and handling of Lithium-Ion cells used widely in Batterypacks for EHV.

- ▲ Heavy wire: 100µm - 500µm
- ▲ Ribbon bonding
- ▲ Tab Bonding
- ▲ Insulated wire

**High power Applications:**

- ▲ Batterypacks, (fused wires)
- ▲ LED's
- ▲ Automotive
- ▲ Many Power Electronics
- ▲ Many more.....

